

nanoSSD

Design Manual

**Total Solution For
Industrial Flash Storage**

Contents

1. INTRODUCTION	6
2. EXTERNAL COMPONENTS SPECIFICATION	7
2.1 POWER SUPPLY.....	8
2.1.1 Power supply.....	8
2.1.2 Power consumption.....	9
2.2 SATA AC COUPLING CAPACITORS.....	10
2.3 RELIABILITY	10
3. MECHANICAL SPECIFICATION.....	11
3.1 BALL AND SIGNAL DESCRIPTION	11
3.2 GPIO TABLE WITH FUNCTION DESCRIPTION	19
4. COMPONENT PLACEMENT AND ROUTING REQUIREMENTS	20
4.1 SATA DIFFERENTIAL SIGNALS.....	20
4.2 POWER DISTRIBUTION.....	20
5. TEMPERATURE AND THERMAL.....	20
6. REFERENCE DESIGN.....	21
6.1 SCHEMATIC.....	21
6.2 LAYOUT GUIDE.....	21
6.3 DEMO BOARD.....	21
7. PRODUCTION GUIDE	21
7.1 PREHEAT	21
7.2 REFLOW PROFILE	21
8. PRODUCT SPECIFICATION / ORDER INFORMATION	23
9. APPENDIX.....	24

TABLE 1 VCC POWER SUPPLY SPECIFICATION	8
TABLE 2 POWER CONSUMPTION	10
TABLE 3 NANOSSD BALL AND SIGNAL DESCRIPTION	18
TABLE 4 NANOSSD GPIO TABLE.....	19
TABLE 5 TEMPERATURE RANGE OF NANOSSD.....	20
TABLE 6 REFLOW PROFILE.....	22
 FIGURE 1 BLOCK DIAGRAM OF NANOSSD.....	8
FIGURE 2 MECHANICAL DRAWING OF NANOSSD.....	11
FIGURE 3 INNODISK SERVERDOM IS AS NANOSSD DEMO BOARD	21

REVISION HISTORY

Revision	Description	Date
Preliminary	First Released	July, 2013
Rev. 0.1	Modify Ball and pin definition	July, 2013
Rev. 0.2	Modify block diagram Modify pin assignment	Sep, 2013
Rev. 0.3	Wording correction Modify pin assignment	Sep, 2013
Rev. 0.4	Modify Power supply info. Modify Block diagram Update attached files Added chapter 10 (table for attachment files)	Nov, 2013
Rev. 0.41	Modify schematic symbol	Nov, 2013
Rev. 0.5	Update product photo, Add "UART" in pin L16, L17 in description, Modify description of attachment table and add nanoSSD demo board design guide item, Change demo board Gerber file name from RAR to txt (due to file compatibility issue in various PDF readers)	Jan, 2014
Rev. 0.51	Update attached file – nanoSSD schematic from Ver. A01 to Ver. A1	Feb, 2014
Rev. 0.6	Update mechanical drawing, Update reflow profile, Update demo board related documents.	Feb, 2014
Rev. 061	Update GPIO table and related attachment	Feb, 2014
Rev. 062	Update nanoSSD design guide (added power sequence info)	JUL, 2014
Rev. 063	add nanoSSD 3SE performance and LBA info	AUG, 2014
Rev. 064	Update 2.1.1 power supply info. (MLC & iSLC) Add 2.1.2 power consumption (MLC & iSLC)	SEP, 2014
Rev. 065	Add 2.1.1 power supply info. (SLC)	OCT, 2014
Rev. 066	Update 2.1.1 power consumption (MLC & iSLC)	NOV, 2014
Rev. 067	Revise MLC and iSLC LBA info.	NOV, 2014
Rev. 068	Added nanoSSD power sequence requirement as attachment. Add SLC 16GB performance info.	DEC, 2014
Rev. 069	Added ESD test report, ROHS and REACH declaration of conformity	JAN, 2015
Rev. 070	Added GPIO table Revised MLC / iSLC performance by using firmware version S141002C.	MAR, 2015
Rev. 1.0	Official release	July, 2015
Rev. 1.1	Modify chapter 8 by adding order information	AUG, 2015
Rev. 1.2	Modify chapter 8, laser marking and order information Modify page 5, 3ME 32GB performance	OCT, 2015

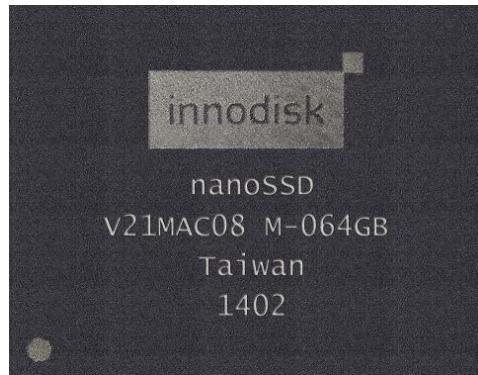
<i>Rev. 1.3</i>	<i>Add 2.3 Reliability section</i>	<i>NOV, 2015</i>
<i>Rev. 1.4</i>	<i>Modify 3.1 GPIO2 and GPIO3 Type and description Modify Chapter 8 description</i>	<i>FEB, 2016</i>
<i>Rev. 1.5</i>	<i>Update 3.1 GPIO description Update Chapter 9 Appendix</i>	<i>MAR, 2016</i>

Innodisk Confidential

1. Introduction

Innodisk nanoSSD is an integrated SATA storage device that combines Innodisk ID167 NAND flash controller and latest NAND flash in a JEDEC MO-276(μSSD) form factor with ball grid array (BGA) package.

The nanoSSD supports SATA III 6Gbps within a tiny dimension, as well as having lower power consumption and being high reliable. It offers an ideal solution for embedded, automotive, medical, gaming and most industrial applications.



Features:

- Compliant with JEDEC MO-276 footprint #11 Specification
- SATA III 6Gbps
- Support NCQ
- Intelligent flash management & real time garbage collection
- Supports S.M.A.R.T, and iSMART utility
- Zero mechanical interference

Performance:

Item		8GB	16GB	32GB	64GB
nanoSSD 3ME	Sequential Read	120 MB/s	240 MB/s	440 MB/s	480 MB/s
	Sequential Write	20 MB/s	40 MB/s	80 MB/s	160 MB/s
nanoSSD 3IE	Sequential Read	250 MB/s	470 MB/s	480 MB/s	N/A
	Sequential Write	70 MB/s	140 MB/s	270 MB/s	N/A

Item		2GB	4GB	8GB	16GB
nanoSSD	Sequential Read	110 MB/s	220 MB/s	340 MB/s	450 MB/s
	Sequential Write	28 MB/s	55 MB/s	110 MB/s	200 MB/s

C.H.S & LBA:

Item		Head	Sector	Cylinder	LBA
nanoSSD	8GB	16	63	13587	13695696
	16GB	16	63	16383	29323728
	32GB	16	63	16383	60579792
	64GB	16	63	16383	121138416

Item		Head	Sector	Cylinder	LBA
nanoSSD	8GB	16	63	13587	13695696
	16GB	16	63	16383	29323728
	32GB	16	63	16383	60579792

Item		Head	Sector	Cylinder	LBA
nanoSSD	2GB	16	63	3897	3928176
	4GB	16	63	7773	7835184
	8GB	16	63	15525	15649200
	16GB	16	63	16383	31277232

2. External Components Specification

The nanoSSD is designed to have minimal peripheral circuits. It requires three power voltage

level and a few passive components to be completely functional. The required specifications for these components are listed below. The reference design section of this document has the list of recommended components which meet these specifications.

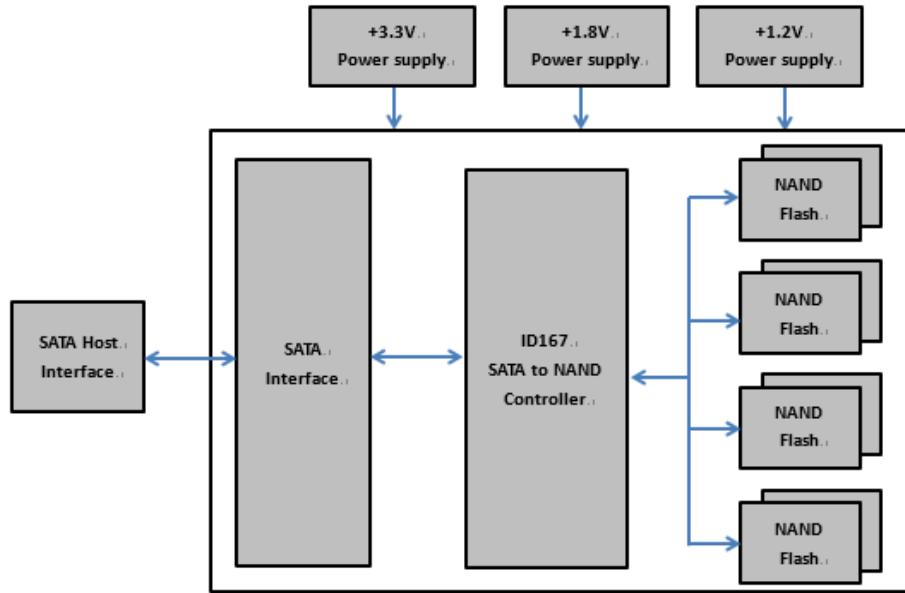


Figure 1 Block diagram of nanoSSD

2.1 Power Supply

This section lists the specifics for input power that is required by the nanoSSD.

2.1.1 Power supply

The power values defined in the table, below, are typical and subject to process and variation of up to $\pm 10\%$.

	Voltage rail	Specification
Input voltage	Main power supply	$3.3V \pm 10\%$
	Flash IO supply	$1.8V \pm 10\%$
	Controller core supply	$1.2V \pm 10\%$

Table 1 VCC Power Supply Specification

2.1.2 Power consumption

Voltage Rail	Parameter	MLC 8GB	MLC 16GB	MLC 32GB	MLC 64GB
SATA 6Gb/s Host interface					
Main power supply	Read (mA)	186	310	408	440
	Write(mA)	194	219	321	560
	Idle(mA)	137	153	158	160
Flash IO supply	Read (mA)	227	240	277	345
	Write(mA)	202	230	260	320
	Idle(mA)	137	161	169	176
Controller core supply	Read (mA)	320	328	335	350
	Write(mA)	303	321	325	330
	Idle(mA)	145	148	152	160

Voltage Rail	Parameter	iSLC 8GB	iSLC 16GB	iSLC 32GB
SATA 6Gb/s Host interface				
Main power supply	Read (mA)	310	408	440
	Write(mA)	219	321	560
	Idle(mA)	153	158	160
Flash IO supply	Read (mA)	240	277	345
	Write(mA)	230	260	320
	Idle(mA)	161	169	176
Controller core supply	Read (mA)	328	335	350
	Write(mA)	321	325	330
	Idle(mA)	148	152	160

Voltage Rail	Parameter	SLC 2GB	SLC 4GB	SLC 8GB	SLC 16GB
SATA 6Gb/s Host interface					
Main power supply	Read (mA)	162	245	292	315
	Write(mA)	140	190	252	440
	Idle(mA)	104	108	113	113
Flash IO supply	Read (mA)	130	155	182	228
	Write(mA)	112	140	156	190
	Idle(mA)	85	92	103	105
Controller core supply	Read (mA)	182	191	213	220
	Write(mA)	182	182	190	191
	Idle(mA)	106	106	106	110

Table 2 Power consumption

2.2 SATA AC Coupling capacitors

10nF X5R MLCC

For more details please refer to design kit

2.3 Reliability

Parameter	Value
Read Cycles	Unlimited Read Cycles
Wear-Leveling Algorithm	Support
Bad Blocks Management	Support
Error Correct Code	Support

TBW (Sequential)

Item	8GB	16GB	32GB	64GB
nanoSSD 3ME	21.6	43.2	86.4	172.8
nanoSSD 3IE	144	288	576	N/A

Item	2GB	4GB	8GB	16GB
nanoSSD 3SE	108	216	432	864

3. Mechanical Specification

Please refer to the attachments for mechanical drawing

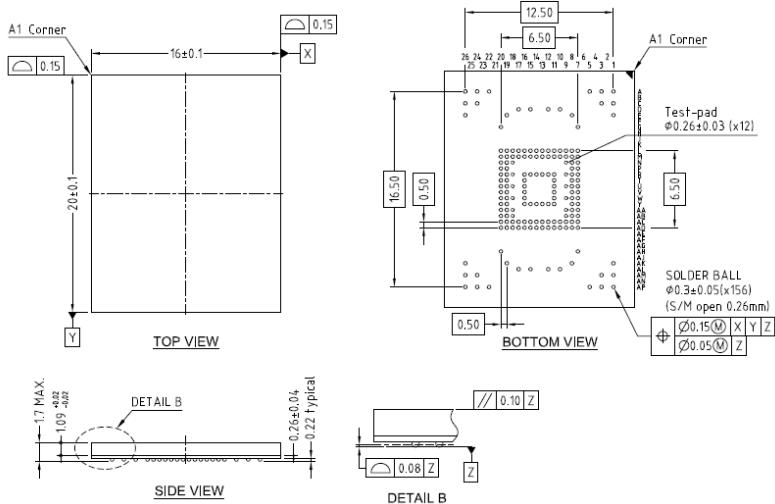


Figure 2 Mechanical drawing of nanoSSD

3.1 Ball and Signal Description

The following table provides the pin definition of the nanoSSD ball grid array.

TYPE: Input - nanoSSD receives signal from host.

TYPE: Output - nanoSSD drives/transmits signal to host device.

TYPE: IO - Signal is bi-directional.

SATA interface signals			
Ball #	Ball name	Type	Description
P7	SATA_RXP	Input	SATA Receive Signal Differential Pair
R7	SATA_RXN	Input	SATA Receive Signal Differential Pair
U7	SATA_TXN	Output	SATA Transmit Signal Differential Pair
V7	SATA_TXP	Output	SATA Transmit Signal Differential Pair

<i>R11</i>	<i>A1V2</i>	<i>Supply</i>	<i>SATA PHY VDDC</i>
<i>T11</i>	<i>A1V2</i>	<i>Supply</i>	<i>SATA PHY VDDC</i>
<i>P8</i>	<i>A1V2</i>	<i>Supply</i>	<i>SATA PHY VDDC</i>
<i>R8</i>	<i>A1V2</i>	<i>Supply</i>	<i>SATA PHY VDDC</i>
<i>T7</i>	<i>AGND</i>	<i>GND</i>	<i>SATA_VSS</i>
<i>N7</i>	<i>AGND</i>	<i>GND</i>	<i>SATA_VSS</i>
<i>W7</i>	<i>AGND</i>	<i>GND</i>	<i>SATA_VSS</i>
<i>Debug signals</i>			
<i>Ball #</i>	<i>Ball name</i>	<i>Type</i>	<i>Description</i>
<i>L16</i>	<i>GPIO 3</i>	<i>Output</i>	<i>RS232 TXD (UART)</i>
<i>L17</i>	<i>GPIO 2</i>	<i>Input</i>	<i>RS232 RXD (UART)</i>
<i>Power supply signals</i>			
<i>Ball #</i>	<i>Ball name</i>	<i>Type</i>	<i>Description</i>
<i>L12</i>	<i>D3V3</i>	<i>Supply</i>	<i>3.3V Power Supply</i>
<i>M11</i>	<i>D3V3</i>	<i>Supply</i>	<i>3.3V Power Supply</i>
<i>R13</i>	<i>D3V3</i>	<i>Supply</i>	<i>3.3V Power Supply</i>
<i>R14</i>	<i>D3V3</i>	<i>Supply</i>	<i>3.3V Power Supply</i>
<i>R15</i>	<i>D3V3</i>	<i>Supply</i>	<i>3.3V Power Supply</i>
<i>R16</i>	<i>D3V3</i>	<i>Supply</i>	<i>3.3V Power Supply</i>
<i>R19</i>	<i>D3V3</i>	<i>Supply</i>	<i>3.3V Power Supply</i>
<i>R20</i>	<i>D3V3</i>	<i>Supply</i>	<i>3.3V Power Supply</i>
<i>T16</i>	<i>D3V3</i>	<i>Supply</i>	<i>3.3V Power Supply</i>
<i>U8</i>	<i>A3V3</i>	<i>Supply</i>	<i>Analog 3.3V</i>
<i>U16</i>	<i>D3V3</i>	<i>Supply</i>	<i>3.3V Power Supply</i>
<i>V8</i>	<i>A3V3</i>	<i>Supply</i>	<i>Analog 3.3V</i>
<i>V11</i>	<i>VCC_IO</i>	<i>Supply</i>	<i>3.3 GPIO Supply</i>

<i>V16</i>	<i>VCCQ</i>	<i>Supply</i>	<i>1.8V VCCQ</i>
<i>W16</i>	<i>VCCQ</i>	<i>Supply</i>	<i>1.8V VCCQ</i>
<i>Y16</i>	<i>VCCQ</i>	<i>Supply</i>	<i>1.8V VCCQ</i>
<i>Y19</i>	<i>VCC_IO</i>	<i>Supply</i>	<i>3.3 GPIO Supply</i>
<i>Y20</i>	<i>D3V3</i>	<i>Supply</i>	<i>3.3V Power Supply</i>
<i>AA19</i>	<i>VCC_IO</i>	<i>Supply</i>	<i>3.3 GPIO Supply</i>
<i>AC8</i>	<i>VCC_IO</i>	<i>Supply</i>	<i>3.3 GPIO Supply</i>
<i>W11</i>	<i>D1V2</i>	<i>Supply</i>	<i>1.2V Power Supply</i>
<i>Y7</i>	<i>D1V2</i>	<i>Supply</i>	<i>1.2V Power Supply</i>
<i>Y8</i>	<i>D1V2</i>	<i>Supply</i>	<i>1.2V Power Supply</i>
<i>Y11</i>	<i>D1V2</i>	<i>Supply</i>	<i>1.2V Power Supply</i>
<i>Y12</i>	<i>D1V2</i>	<i>Supply</i>	<i>1.2V Power Supply</i>
<i>Y13</i>	<i>D1V2</i>	<i>Supply</i>	<i>1.2V Power Supply</i>
<i>AA7</i>	<i>D1V2</i>	<i>Supply</i>	<i>1.2V Power Supply</i>

Ground (GND) signals

<i>Ball #</i>	<i>Ball name</i>	<i>Type</i>	<i>Description</i>
<i>L7</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>L8</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>L11</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>L19</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>L20</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>M7</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>M19</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>M20</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>N8</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>N19</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>

<i>P19</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>P20</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>R12</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>T8</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>U11</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>U19</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>U20</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>V19</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>Y14</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>Y15</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>AB7</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>AC7</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>AC20</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>AD7</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>AD8</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>AD19</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>AD20</i>	<i>VSS</i>	<i>GND</i>	<i>Ground</i>
<i>Analog signals</i>			
<i>L9</i>	<i>XTALOUT</i>	<i>Output</i>	<i>25MHz Crystal out</i>
<i>M10</i>	<i>XTALIN</i>	<i>Input</i>	<i>25MHz Crystal in</i>
<i>Do not use (DNU) signals</i>			
<i>Ball #</i>	<i>Ball name</i>	<i>Type</i>	<i>Description</i>
<i>M8</i>	<i>TMEN</i>	<i>DNU</i>	<i>Do not use</i>
<i>M16</i>	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
<i>AC13</i>	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
<i>AC10</i>	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>

AA8	<i>Flash Vref</i>	<i>DNU</i>	<i>Do not use</i>
AD9	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
AD11	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
AD13	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
L14	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
M12	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
M14	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
M15	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
M17	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
M18	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
N20	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
T19	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
T20	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
V20	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
W8	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
W19	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
W20	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
AB8	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
AB19	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
AB20	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
AC12	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
AC15	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
AC17	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
AC18	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
AC19	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>
AD14	<i>NC</i>	<i>DNU</i>	<i>Do not use</i>

<i>Reserved signals</i>			
<i>Ball #</i>	<i>Ball name</i>	<i>Type</i>	<i>Description</i>
<i>L15</i>	<i>GPIO 0</i>	<i>Output</i>	<i>SDA</i>
<i>AD10</i>	<i>GPIO 1</i>	<i>Output</i>	<i>SCL</i>
<i>AD16</i>	<i>GPIO 4</i>	<i>Input</i>	<i>Reserved</i>
<i>L18</i>	<i>GPIO 5</i>	<i>In & Out</i>	<i>Load mode</i>
<i>AD18</i>	<i>GPIO 6</i>	<i>Output</i>	<i>Reserved</i>
<i>AC14</i>	<i>GPIO 7</i>	<i>Input</i>	<i>Reserved</i>
<i>AC11</i>	<i>GPIO 8</i>	<i>Output</i>	<i>Reserved</i>
<i>AD17</i>	<i>GPIO 9</i>	<i>Output</i>	<i>Reserved</i>
<i>AC16</i>	<i>GPIO 10</i>	<i>Output</i>	<i>Reserved</i>
<i>AD15</i>	<i>GPIO 11</i>	<i>Output</i>	<i>Reserved</i>
<i>AC9</i>	<i>GPIO 12</i>	<i>Input</i>	<i>Reserved</i>
<i>AA20</i>	<i>GPIO 13</i>	<i>Output</i>	<i>PHY LED</i>
<i>M13</i>	<i>GPIO 14</i>	<i>Output</i>	<i>DAS</i>
<i>AD12</i>	<i>GPIO 15</i>	<i>Input</i>	<i>Write Protect</i>
<i>L10</i>	<i>GPIO 16</i>	<i>Output</i>	<i>Reserved</i>
<i>L13</i>	<i>GPIO 17</i>	<i>Input</i>	<i>Low power detect</i>
<i>M9</i>	<i>RESET</i>	<i>Input</i>	<i>SSD Reset</i>
<i>Mechanical ground balls</i>			
<i>Ball #</i>	<i>Ball name</i>	<i>Type</i>	<i>Description</i>
<i>A1</i>	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
<i>A3</i>	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
<i>A5</i>	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
<i>A22</i>	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
<i>A24</i>	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>

A26	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
C1	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
C3	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
C24	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
C26	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
D10	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
D12	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
D15	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
D17	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
E1	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
E8	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
E19	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
E26	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
G7	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
G20	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AH7	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AH20	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AK1	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AK8	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AK19	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AK26	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AL10	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AL12	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AL15	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AL17	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AM1	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>

AM3	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AM24	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AM26	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AP1	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AP3	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AP5	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AP22	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AP24	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>
AP26	<i>ME. GND</i>	<i>GND</i>	<i>Ground</i>

Table 3 nanoSSD Ball and Signal Description

3.2 GPIO table with function description

Item	Function	pin type	Description
GPIO0	Thermal Sensor SDA	output	For I2C interface thermal sensor IC
GPIO1	Thermal Sensor SCL	output	For I2C interface thermal sensor IC
GPIO2	UART-RX	input	UART message for debugging
GPIO3	UART-TX	output	UART message for debugging
GPIO4	Reserved	input	No function
GPIO5	Loader Mode	input	Strapping input type when power on, Set it in high for entering loader mode, default is low.
GPIO6	NAND type0	input	for internal NAND flash type, leave it N.C.
GPIO7	NAND type1	input	for internal NAND flash type, leave it N.C.
GPIO8	Reserved	input	No function.
GPIO9	Reserved	input	For internal frequency type setting, leave it N.C.
GPIO10	Reserved	input	For internal frequency type setting, leave it N.C.
GPIO11	Reserved	input	For internal frequency type setting, leave it N.C.
GPIO12	Reserved	input	No function.
GPIO13	PHY LED	output	When SATA connected, it will output high for lighting LED.
GPIO14	DAS LED	output	When SSD is transferred data, it will output high and low for indicating data access.
GPIO15	FW_WP	input	Low active, it will be entering firmware write protection function if pull low
GPIO16	Reserved	input	no function
GPIO17	PWR loss	input	Low active, it will running internal cache data protect function when it triggered.

Table 4 nanoSSD GPIO table

4. Component Placement and Routing Requirements

This section states component placement and routing requirements of nanoSSD. Please refer to attachments for reference design.

4.1 SATA Differential Signals

To comply with SATA interface specifications, the SATA differential lines must have 100 Ohm differential impedance.

4.2 Power Distribution

- The SATA AC coupling capacitors should be placed close to the host.
- All decoupling capacitors and filters must be placed as close to the power supply pads as possible.
- The PCB stack up must include at least one solid ground plane.
- All traces, except supply/ground and SATA differential pair, should have 50 ohm single-ended impedance.

5. Temperature and Thermal

The maximum operating temperature of the nanoSSD is listed below, and must be maintained at any time the device is active.

Temperature	Range
Operating	<i>Standard Grade: 0°C to +70°C</i> <i>Industrial Grade: -40°C to +85°C</i>
	<i>*The industrial grade item is only available in SLC item.</i>
Storage	-55°C to +95°C

Table 5 Temperature range of nanoSSD

Below are some recommendations for PCB design to lowest effect of thermal.

- Maximize copper thickness and trace width for all pins to thermal features such as thermal vias, thermal side rails, and thermal conduction screw holes.
- Copper ground/supply planes in the PCB can provide very effective heat dissipation for the

IC package. To maximize effectiveness, thermal vias should be added to connect the package's mechanical ground balls to the ground plane. There should be at least one thermal via allocated for each MGB of the package. The plating thickness of vias should be maximized to optimize thermal conduction.

6. Reference Design

A reference design using the nanoSSD has been provided here to help with the integration. All peripheral circuits are included in the design and meet specifications laid out in the earlier sections of this document. We recommend this circuit design to match the reference design as closely as possible. The schematic and bill of materials (BOM) are listed in attachments.

6.1 SCHEMATIC

Please refer to attachments for schematic files.

6.2 Layout guide

Refer to attached (NanoSSD design guide)

6.3 Demo board



Figure 3 Innodisk ServerDOM is as nanoSSD Demo board

7. Production guide

7.1 Preheat

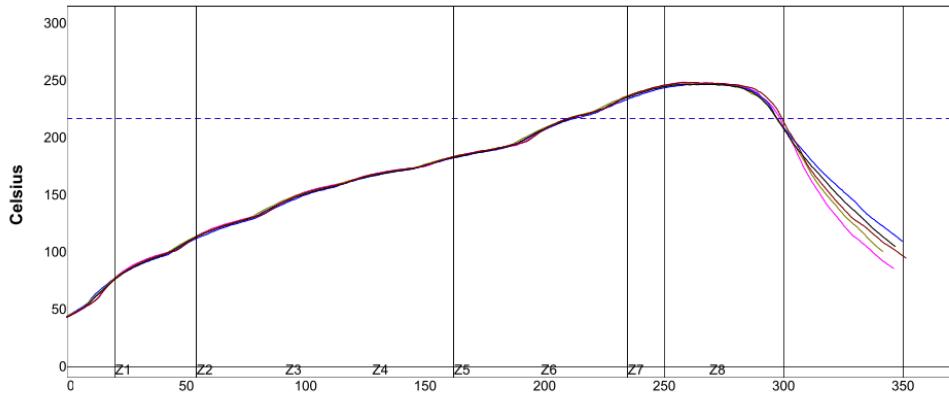
Before printed circuit board assembly, a process of preheat is requested.

Preheat condition: 16 HRs with 125°C

7.2 Reflow Profile

Please refer to attachments for reflow profile.

Setpoints (Celsius)								
Zone	1	2	3	4	5	6	7	8
Top	100	130	165	170	180	230	255	245
Bottom	100	130	165	170	180	230	255	245
Conveyor Speed (cm/min): 65.0								



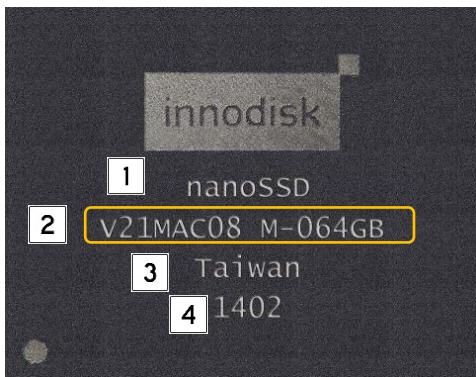
PWI= 97%	ax	Rising Slope	ax	Falling Slope	heat	30-110	ak Time	110-1eflow	Time /21	Peak Temp	ope1 (30-110	ope2 (217-255	Time	150-217		
2	1.84	49%	-3.85	-90%	50.97	27%	44.64	-2%	88.53	95%	248.81	38%	1.84	68%	0.91	-73%	113.84	79%
3	1.67	25%	-2.70	-13%	52.28	31%	47.50	17%	84.64	82%	247.17	22%	1.67	52%	0.85	-80%	112.70	76%
4	1.74	34%	-3.28	-52%	50.93	27%	46.26	8%	87.52	92%	247.40	24%	1.74	58%	0.87	-77%	112.90	76%
5	1.73	32%	-2.83	-22%	50.55	26%	47.44	16%	86.53	88%	246.95	20%	1.73	57%	0.86	-79%	112.13	74%
6	1.77	39%	-3.44	-63%	51.04	28%	45.85	6%	89.09	97%	248.43	34%	1.77	61%	0.91	-72%	112.75	76%
Delta	0.17		1.15		1.73		2.86		4.45		1.86		0.17		0.06		1.71	

Process Window:

Solder Paste:	System Default for Reflow		
Statistic Name	Low Limit	High Limit	Units
Max Rising Slope (Target=1.5) (Calculate Slope over 20 Seconds)	0.7	2.2	Degrees/Second
Slope1 (Target=1.1) Between 30.0 and 110.0 (Calculate Slope over 20 Seconds)	0	2.2	Degrees/Second
Slope2 (Target=1.5) Between 217.0 and 255.0 (Calculate Slope over 20 Seconds)	0.7	2.2	Degrees/Second
Max Falling Slope (Calculate Slope over 20 Seconds)	-4	-1	Degrees/Second
Preheat Time 30-110C	0	80	Seconds
Soak Time 110-150C	30	60	Seconds
Soak Time 150-217C (2)	60	120	Seconds
Time Above Reflow - 217C	30	90	Seconds
Peak Temperature	235	255	Degrees Celsius

Table 6 Reflow Profile

8. Product specification / Order information



<i>Line</i>	<i>Description</i>
1	Product name
2	Product specification
3	Place of origin
4	Date code (YYWW)

<i>Product Specification code</i>	<i>Description</i>	<i>Part number</i>
V21MAC01 M-008GB	<i>nanoSSD 3ME 08GB, 1CH, MLC</i>	DENSD-08GD06SCASY
V21MAC02 M-016GB	<i>nanoSSD 3ME 16GB, 2CH, MLC</i>	DENSD-16GD06SCADY
V21MAC04 M-032GB	<i>nanoSSD 3ME 32GB, 4CH, MLC</i>	DENSD-32GD06SCAQY
V21MAC08 M-064GB	<i>nanoSSD 3ME 64GB, 4CH, MLC</i>	DENSD-64GD06SCAQY
V21MAC02 I-008GB	<i>nanoSSD 3IE 08GB, 2CH, MLC</i>	DHNSD-08GD062CADY
V21MAC04 I-016GB	<i>nanoSSD 3IE 16GB, 4CH, MLC</i>	DHNSD-16GD062CAQY
V21MAC08 I-032GB	<i>nanoSSD 3IE 32GB, 4CH, MLC</i>	DHNSD-32GD062CAQY
V21SAA01 S-002GB	<i>nanoSSD 3SE 02GB, 1CH SLC</i>	DENSD-02GD06SCASX DENSD-02GD06SWASX
V21SAA02 S-004GB	<i>nanoSSD 3SE 04GB, 2CH SLC</i>	DENSD-04GD06SCADX DENSD-04GD06SWADX
V21SAA04 S-008GB	<i>nanoSSD 3SE 08GB, 4CH SLC</i>	DENSD-08GD06SCAQX DENSD-08GD06SWAQX
V21SAA08 S-016GB	<i>nanoSSD 3SE 16GB, 4CH SLC</i>	DENSD-16GD06SCAQX DENSD-16GD06SWAQX

9. Appendix

File name	Description
<i>gerber-4DADP000X42_rar</i>	<i>Demo board Gerber file</i> <i>(Due to PDF file compatibility issue, please change file extension from .txt to .rar and decompress with Winrar or 7-zip)</i>
<i>BGA156P0D5-16X20.dra</i>	<i>Mechanical drawing</i>
<i>BGA156P0D5-16X20.dxf</i>	<i>Component symbol</i>
<i>BGA156P0D5-16X20.psm</i>	<i>Component symbol</i>
<i>Innodisk nanoSSD ESD test report</i>	<i>nanoSSD ESD test report</i>
<i>NANOSSD_BGA156_Reference_A3_160329.DSN</i>	<i>Schematic</i>
<i>nanossd_bga156_reference_a3_160329.pdf</i>	<i>Schematic</i>
<i>nanoSSD design guide.pdf</i>	<i>design guide</i>
<i>nanoSSD power sequence requirement.pdf</i>	<i>Power sequence information</i>
<i>nano-ssd_16x20_156BALLS.pdf</i>	<i>Mechanical drawing</i>
<i>Reflow profile en.pdf</i>	<i>Reflow profile</i>
<i>REACH declaration of conformity</i>	<i>Declaration</i>
<i>ROHS declaration of conformity</i>	<i>Declaration</i>

*To get the files list above, please check the attachment of this PDF.